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**LEEBOND 37-75
 EPOXY LEAD WIRE SEALANT**

Description

LEEBOND 37-75 is a proprietary two-part epoxy adhesive used in both electrical-grade potting and structural adhesive applications. Cured systems demonstrate excellent toughness, impact resistance and exceptional bond strength for hard to bond to substrates. This system can be cured at both room temperature or accelerated with modest heating.

Longer cure schedules may be needed when curing thin sections or where the epoxy is adjacent to a mass of material that will act as a heat sink.

TYPICAL PROPERTIES		
	Part A	Part B
Appearance	Red liquid	Amber liquid
Viscosity, 25°C, cps	15,000	3,900
Density, lbs/gal	12.3	8.0
Shelf Life, months	12	12

TYPICAL HANDLING PROPERTIES		
	Part A	Part B
Mix Ratio, by volume	100	50
, by weight	100	34
Mixed Color	Red	
Gel Time, 25°C, 100 g, min	51	
Work Life, 25°C, 20 g, min	60 – 90	

Directions for Use

Parts to be bonded should be clean and free of all greases and oils. All surfaces to be bonded should also be dry. The adhesive can be applied using any of the conventional manual or automated mechanical methods.

Storage and Handling

Some individuals may be sensitive to epoxy compounds. Care should be taken to minimize contact. If skin contact occurs wash with soap and water. If eye contact occurs, flush with copious quantities of water.

The gel time of LEEBOND 37-75 depends on temperature and mass of material. Large masses and/or elevated temperatures will shorten the gel time. Cure can be accomplished at room temperature or with heat if faster cures are desired. Typical cure schedules for small masses are:

- 50°C 1 – 2 hours
- 65°C 40 – 60 minutes

Keep containers closed when not in use to prevent contamination. Minimize exposure to Part B to air and moisture.